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PHIXEL DWR
Die & Wire bond Reel inspection

Application

- Inspection of lead-frame substrate to detect post die bond and wire bond defect

Key Feature

- High speed fully auto wire loop/profile inspection
- Min 5MP camera for 3D inspection
- Laser cut option for reject handling
- Post inspection after reject laser handling
- Inspection Time: 7µm resolution with 4cm/second
- SEMI standard with SECS/GEM interface
- Sophisticated defect mode classification
- Lead frame width 17mm to 32mm
- AOI cellular network architecture for recipe and emap management
- Option: real-time data feeding to MES and eSPC
- Option: auto email alert (defect / batch summary)

3D Post-Wiebond Reel-to-Reel Inspection

Imaging System

Camera	5M pixels area camera monochrome
Number of camera	3
Resolution / Field of View	3.7 µm/pixel, FOV: 9mm
Min object detection	15 µm
Lighting	Blue bar light / dome light + back panel light

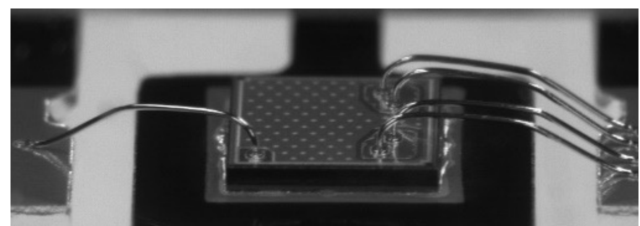

Image from camera

Inspection Categories

Program Mode:	Fast programming for common reject criteria		
Reject treatment:	Electronic map and laser		
Inspection View:	Top and side view		
Inspection items:	**Die defects:** - Foreign material - Die placement - Glue on chip	**Wire defects:** - Ball shift - Sweep wire - Loop height - Sagging wire - Stray wire - Broken wire - Missing wire - Stitch off - Stitch offset	**Lead-frame defects:** - Lead deformation - Lead shift - Lead lift up - Missing chip

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